

## FL6000

*Component Lead Tinning Flux*



### Product Description

Hasaconi FL6000 Component Lead Tinning Flux is incorporated with organic activators to provide improved solderability by reducing the surface tension of solder during the tinning process. The key objective of this flux is to provide a replacement for RA and RMA fluxes, which are considered potentially corrosive in certain applications and yet provides the necessary activity for defect free soldering.

### Application

FL6000 is specially formulated for component lead tinning process. Recommended preheat temperature is 80 – 100 °C.

### Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

### Recommended Solvent

Asahi's complementary Solvent #6000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

### Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

### Storage

Under proper storage condition, FL6000 can be stored for about 6 months. FL6000 is flammable. Keep away from all sources of heat, sparks and flame.

### Packaging

Available in 18kg/carboy.

### Specification

Item	Result
State	Liquid
Colour	Colourless
Specific Gravity @ 25°C	0.823 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	2.0 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	0.08 +/- 0.01 wt%
<small>JIS Z 3197 8.1.4.2.1</small>	
Acid Value Test	14.5 +/- 1.0 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Water Extract Resistivity	> 1 x 10 <sup>4</sup> Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
<small>JIS Z 3197 8.5.3</small>	> 1 x 10 <sup>11</sup> Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
<small>IPC-TM-650 2.6.14.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROM1
<small>IPC J-STD-004</small>	
Spread Factor	> 85% (SnPb)
<small>JIS Z 3197 8.3.1.1</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	
Surface Finish	Shiny

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